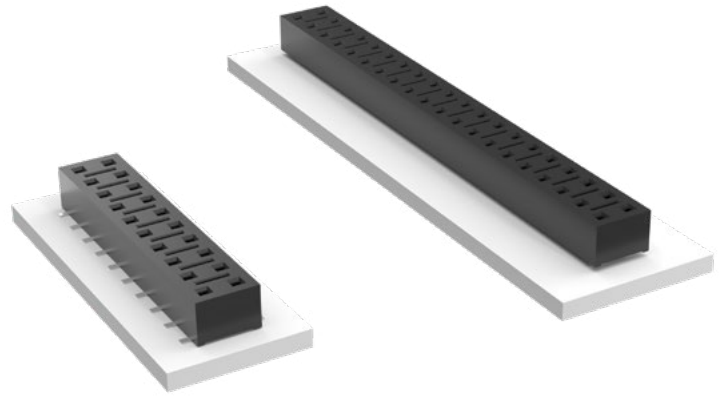


COST-EFFECTIVE RELIABLE SOCKET

(2.54 mm) .100" PITCH • HLE SERIES



HLE

Board Mates:

TSW, MTSW, DW, EW,
ZW, TLW, TSM, MTLW, HW

SPECIFICATIONS

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

BeCu

Plating:

Au or Sn over
50 μ" (1.27 μm) Ni

Current Rating (HLE/TSM):

4.1 A per pin
(2 pins powered)

Voltage Rating:

400 VAC

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(1.78 mm) .070" to
(3.43 mm) .135" pass-through,
or (2.59 mm) .102" min
plus board thickness for
bottom entry

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-20)
(0.15 mm) .006" max (21-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

ALSO AVAILABLE

MOQ Required

Other Platings

Note:

Some lengths, styles and
options are non-standard,
non-returnable.



02 thru 50

-F
= Gold flash on
contact,
Matte Tin on tail

-L
= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

Leave blank for
Surface Mount
(Requires -BE for
Bottom Entry)

-TE
= Through-hole
Top Entry

-PE
= Through-hole
Pass-through
Entry
(Requires -BE for
Bottom Entry)

-BE
= Bottom Entry
(Not available
with -TE)

-A
= Alignment Pin
(4 positions min.)
Metal or plastic at
Samtec discretion
(Not available with
-TE, -PE & -LC)

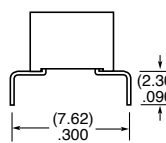
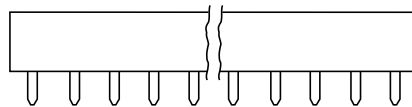
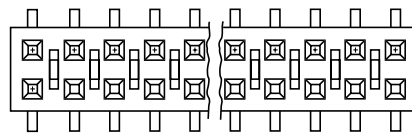
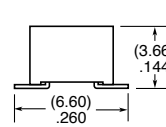
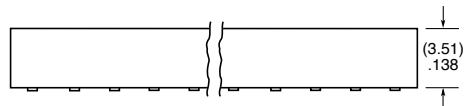
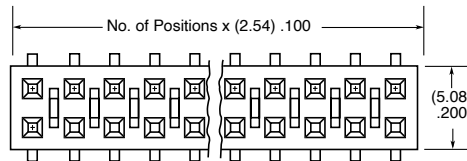
-LC
= Locking Clip
(2 positions min.)
(Not available with -A)
(Manual placement
required)

-K
= (6.50 mm)
.256" DIA
Polyimide Film
Pick & Place Pad
(3 positions min.)
Not available
with -TE or
-PE tail option

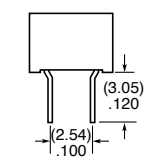
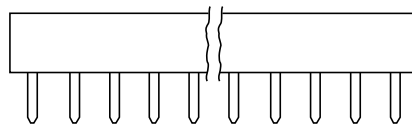
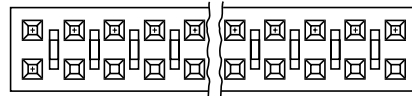
-P
= Metal Pick
& Place Pad
(3 positions min.)

-TR
= Tape & Reel
(29 positions max.)

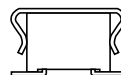
-FR
= Full Reel
Tape & Reel
(must order max.
quantity per reel;
contact Samtec for
quantity breaks)



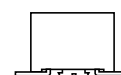
-PE



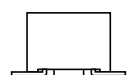
-TE



-P



-LC



-A